Low-Voltage 1.8V/2.5V/3.3V 16-Bit Buffer

With 3.6 V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The 74VCX16244 is an advanced performance, non-inverting 16-bit buffer. It is designed for very high-speed, very low-power operation in 1.8 V, 2.5 V or 3.3 V systems.

When operating at 2.5 V (or 1.8 V) the part is designed to tolerate voltages it may encounter on either inputs or outputs when interfacing to 3.3 V busses. It is guaranteed to be overvoltage tolerant to 3.6 V.

The 74VCX16244 is nibble controlled with each nibble functioning identically, but independently. The control pins may be tied together to obtain full 16-bit operation. The 3-state outputs are controlled by an Output Enable (\overline{OEn}) input for each nibble. When \overline{OEn} is LOW, the outputs are on. When \overline{OEn} is HIGH, the outputs are in the high impedance state.

Features

- Designed for Low Voltage Operation: $V_{CC} = 1.65 \text{ V} 3.6 \text{ V}$
- 3.6 V Tolerant Inputs and Outputs
- High Speed Operation: 2.5 ns max for 3.0 V to 3.6 V

3.0 ns max for 2.3 V to 2.7 V 6.0 ns max for 1.65 V to 1.95 V

• Static Drive: ±24 mA Drive at 3.0 V

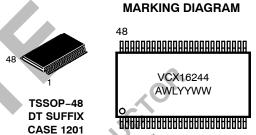
±18 mA Drive at 2.3 V ±6 mA Drive at 1.65 V

- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0$ V
- Near Zero Static Supply Current in All Three Logic States (20 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±250 mA @ 125°C
- ESD Performance: Human Body Model >2000 V; Machine Model >200 V
- All Devices in Package TSSOP are Inherently Pb-Free*



ON Semiconductor®

http://onsemi.com



A M/I

Assembly Location

L = Wafer Lot Y = Year

= Work Week

ORDERING INFORMATION

Device	Package	Shipping [†]
74VCX16244DT	TSSOP (Pb-Free)	39 / Rail
74VCX16244DTR	TSSOP (Pb-Free)	2500 / Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

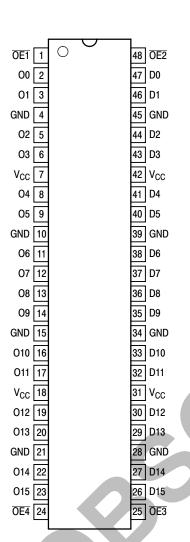


Figure 1. 48-Lead Pinout (Top View)

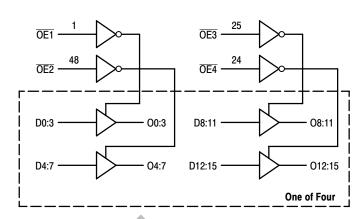


Figure 2. Logic Diagram

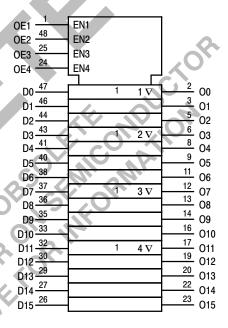


Figure 3. IEC Logic Diagram

Table 1. PIN NAMES

Pins	Function
OEn	Output Enable Inputs
D0-D15	Inputs
O0-O15	Outputs

TRUTH TABLE

OE1	D0:3	O0:3	OE2	D4:7	O4:7	OE3	D8:11	O8:11	OE4	D12:15	012:15
L	L	L	L	L	L	L	L	L	L	L	L
L	Н	Н	L	Н	Н	L	Н	Н	L	Н	Н
Н	Х	Z	Н	Х	Z	Н	Х	Z	Н	Х	Z

- H = High Voltage Level;
- L = Low Voltage Level;
- Z = High Impedance State;
- X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +4.6		V
VI	DC Input Voltage	$-0.5 \le V_{ } \le +4.6$		V
Vo	DC Output Voltage	$-0.5 \le V_{O} \le +4.6$	Output in 3-State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1; Outputs Active	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
lok	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Io	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
V _{CC}	Supply Voltage Data Ret	Operating ention Only		3.3 3.3	3.6 3.6	V
VI	Input Voltage	Q	-0.3		3.6	V
V _O	Output Voltage (A	ctive State) (3-State)	0		V _{CC} 3.6	V
I _{OH}	HIGH Level Output Current, V _{CC} = 3.0 V - 3.6 V	0			-24	mA
I _{OL}	LOW Level Output Current, V _{CC} = 3.0 V - 3.6 V	0,50,			24	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 2.3 V - 2.7 V				-18	mA
I _{OL}	LOW Level Output Current, V _{CC} = 2.3 V - 2.7 V				18	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 1.65 V - 1.95 V				-6	mA
I _{OL}	LOW Level Output Current, V _{CC} = 1.65 V - 1.95 V				6	mA
T _A	Operating Free-Air Temperature		-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from 0.8 V to 2.0 V, V_{IN}	_{CC} = 3.0 V	0		10	ns/V
	Imput Transition rise of Fair rate, VIN IIIII 10.8 V to 2.0 V, V					

^{1.} IO absolute maximum rating must be observed.

DC ELECTRICAL CHARACTERISTICS

			$T_A = -40^\circ$	C to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2)	1.65 V ≤ V _{CC} < 2.3 V	0.65 x V _{CC}		V
		2.3 V ≤ V _{CC} ≤ 2.7 V	1.6		
		2.7 V < V _{CC} ≤ 3.6 V	2.0		
V_{IL}	LOW Level Input Voltage (Note 2)	1.65 V ≤ V _{CC} < 2.3 V		0.35 x V _{CC}	V
		2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	
		2.7 V < V _{CC} ≤ 3.6 V		0.8	
V _{OH}	HIGH Level Output Voltage	1.65 V ≤ V_{CC} ≤ 3.6 V; I_{OH} = -100 μ A	V _{CC} - 0.2		V
		V _{CC} = 1.65 V; I _{OH} = -6 mA	1.25		
		V _{CC} = 2.3 V; I _{OH} = -6 mA	2.0		
		$V_{CC} = 2.3 \text{ V}; I_{OH} = -12 \text{ mA}$	1.8		
		V _{CC} = 2.3 V; I _{OH} = -18 mA	1.7	76	
		$V_{CC} = 2.7 \text{ V}; I_{OH} = -12 \text{ mA}$	2.2		
		V _{CC} = 3.0 V; I _{OH} = -18 mA	2.4		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -24 \text{ mA}$	2.2		
V_{OL}	LOW Level Output Voltage	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$	4.10	0.2	V
		V _{CC} = 1.65 V; I _{OL} = 6 mA	.0.	0.3	
		$V_{CC} = 2.3 \text{ V}; I_{OL} = 12 \text{ mA}$		0.4	
		V _{CC} = 2.3 V; I _{OL} = 18 mA		0.6	
		$V_{CC} = 2.7 \text{ V; } I_{OL} = 12 \text{ mA}$		0.4	
		$V_{CC} = 3.0 \text{ V}; I_{OL} = 18 \text{ mA}$		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
I _I	Input Leakage Current	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{I} \le 3.6 \text{ V}$		±5.0	μΑ
l _{OZ}	3-State Output Current	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{ 0 V} \le \text{V}_{O} \le 3.6 \text{ V};$ $\text{V}_{I} = \text{V}_{IH} \text{ or V}_{IL}$		±10	μΑ
I _{OFF}	Power-Off Leakage Current	V _{CC} = 0 V; V _I or V _O = 3.6 V		10	μΑ
I _{CC}	Quiescent Supply Current (Note 3)	$1.65 \text{ V} \le \text{V}_{\text{CC}} \le 3.6 \text{ V}; \text{V}_{\text{I}} = \text{GND or V}_{\text{CC}}$		20	μΑ
		$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 3.6 \text{ V} \le \text{V}_{I}, \text{V}_{O} \le 3.6 \text{ V}$		±20	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	$2.7 \text{ V} < \text{V}_{\text{CC}} \le 3.6 \text{ V}; \text{V}_{\text{IH}} = \text{V}_{\text{CC}} - 0.6 \text{ V}$		750	μΑ

^{2.} These values of V₁ are used to test DC electrical characteristics only.

3. Outputs disabled or 3–state only.

AC CHARACTERISTICS (Note 4; $t_R = t_F = 2.0 \text{ ns}$; $C_L = 30 \text{ pF}$; $R_L = 500 \Omega$)

					T _A = -40	°C to +85°C	;		
			V _{CC} = 3.0	V to 3.6 V	V _{CC} = 2.3	V to 2.7 V	V _{CC} = 1.65	V to 1.95 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Input-to-Output	1	0.8 0.8	2.5 2.5	1.0 1.0	3.0 3.0	1.5 1.5	6.0 6.0	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	4.1 4.1	1.5 1.5	8.2 8.2	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	3.8 3.8	1.5 1.5	6.8 6.8	ns
t _{OSHL}	Output-to-Output Skew (Note 5)			0.5 0.5		0.5 0.5		0.75 0.75	ns

- 4. For $C_L = 50$ pF, add approximately 300 ps to the AC maximum specification.
- Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

AC CHARACTERISTICS ($t_R = t_F = 2.0 \text{ ns}$; $C_L = 50 \text{ pF}$; $R_L = 500 \Omega$)

				T _A = -40°C	c to +85°C		
			V _{CC} = 3.0	V to 3.6 V	V _{CC} =	2.7 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Input-to-Output	3	1.0 1.0	3.0 3.0		3.6 3.6	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	4	1.0 1.0	4.4 4.4		5.4 5.4	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	4	1.0 1.0	4.1 4.1		4.6 4.6	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 6)), (),	0.5 0.5		0.5 0.5	ns

^{6.} Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (tosht) or LOW-to-HIGH (tosth); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	Typical (T _A = +25°C)	Unit
V _{OLP}	Dynamic LOW Peak Voltage	V_{CC} = 1.8 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	0.25	V
	(Note 7)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	0.6	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	0.8	
V _{OLV}	Dynamic LOW Valley Voltage	V_{CC} = 1.8 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.25	V
	(Note 7)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.6	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-0.8	
V _{OHV}	Dynamic HIGH Valley Voltage	$V_{CC} = 1.8 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	1.5	V
	(Note 8)	$V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	1.9	
		$V_{CC} = 3.3 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	2.2	

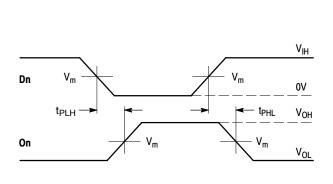
^{7.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

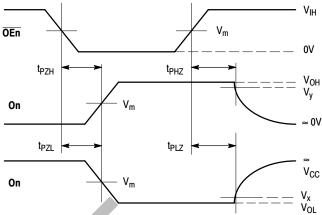
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition Typical	Unit
C _{IN}	Input Capacitance	Note 9 6	pF
C _{OUT}	Output Capacitance	Note 9 7	pF
C _{PD}	Power Dissipation Capacitance	Note 9, 10MHz 20	pF

^{9.} $V_{CC} = 1.8$, 2.5 or 3.3 V; $V_{I} = 0$ V or V_{CC} .

^{8.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the HIGH state.





WAVEFORM 1 - PROPAGATION DELAYS

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

 t_R = t_F = 2.0 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

Figure 4. AC Waveforms

Table 2. AC WAVEFORMS

		Vcc	/ N
Symbol	3.3 V ± 0.3 V	2.5 V ± 0.2 V	1.8 V ± 0.15 V
V _{IH}	2.7 V	V _{CC}	Vcc
V _m	1.5 V	V _{CC} /2	V _{CC} /2
V _x	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V
V _y	V _{OH} - 0.3 V	V _{OH} – 0.15 V	V _{OH} – 0.15 V

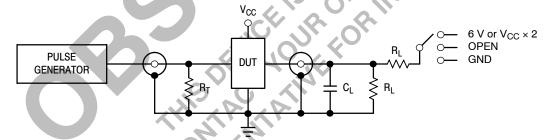


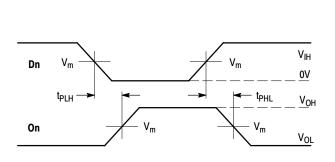
Figure 5. Test Circuit

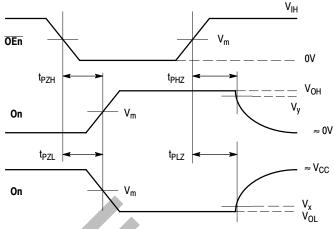
Table 3. TEST CIRCUIT

TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6 V at V_{CC} = 3.3 ± 0.3 V; $V_{CC} \times$ 2 at V_{CC} = 2.5 ± 0.2 V; 1.8 ± 0.15 V
t _{PZH} , t _{PHZ}	GND

 C_L = 30 pF or equivalent (Includes jig and probe capacitance) R_L = 500 Ω or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)





WAVEFORM 3 - PROPAGATION DELAYS

 t_R = t_F = 2.0 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

WAVEFORM 4 - OUTPUT ENABLE AND DISABLE TIMES

 t_{R} = t_{F} = 2.0 ns, 10% to 90%; f = 1 MHz; t_{W} = 500 ns

Figure 6. AC Waveforms

Table 4. AC WAVEFORMS

	V _{CC}		
Symbol	3.3 V ± 0.3 V	2.7 V	
V _{IH}	2.7 V	2.7 V	
V _m	1.5 V	1.5 V	
V _x	V _{OL} + 0.3 V	V _{OL} + 0.3 V	
V _y	V _{OH} - 0.3 V	V _{OH} – 0.3 V	

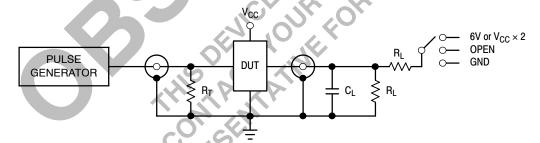


Figure 7. Test Circuit

Table 5. TEST CIRCUIT

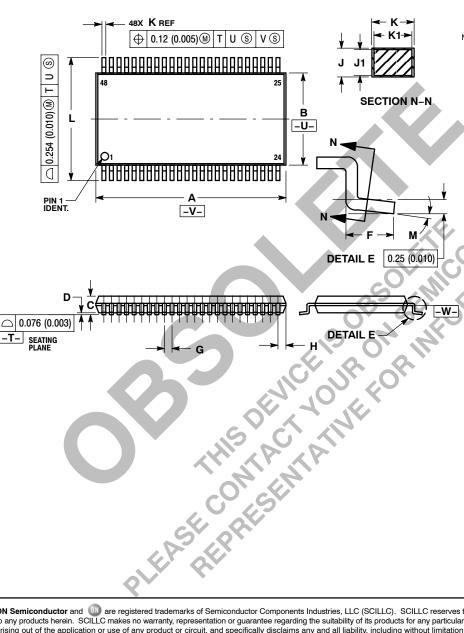
TEST	SWITCH	
t _{PLH} , t _{PHL}	Open	
t _{PZL} , t _{PLZ}	6 V at V_{CC} = 3.3 ± 0.3 V; V_{CC} × 2 at V_{CC} = 2.5 ± 0.2 V; 1.8 ± 0.15 V	
t _{PZH} , t _{PHZ}	GND	

 C_L = 50 pF or equivalent (Includes jig and probe capacitance) R_L = 500 Ω or equivalent

 $R_T^2 = Z_{OUT}$ of pulse generator (typically 50 Ω)

PACKAGE DIMENSIONS

TSSOP DT SUFFIX CASE 1201-01 **ISSUE A**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. DIMENSION K DOES NOT INCLUDE DAMBAR
- PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. SHALL BE 0.08 (0.003) TOTAL IN
 EXCESS OF THE K DIMENSION AT MAXIMUM
 MATERIAL CONDITION.
- MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 DIMENSIONS A AND B ARE TO BE
 DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	12.40	12.60	0.488	0.496
В	6.00	6.20	0.236	0.244
C		1.10		0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.50 BSC		0.0197 BSC	
H	0.37	-	0.015	
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.17	0.27	0.007	0.011
K1	0.17	0.23	0.007	0.009
٦	7.95	8.25	0.313	0.325
M	0 °	8 °	0 °	8 °

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